

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ050N03LS G	**Issued**	11. May 2021
MA#	MA001684532		
Package	PG-TSDSON-8-2	**Weight***	39.77 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.213	3.05	3.05	30491	30491
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		53	
	non noble metal	zinc	7440-66-6	0.008	0.02		211	
	non noble metal	iron	7439-89-6	0.168	0.42		4216	
	non noble metal	copper	7440-50-8	6.808	17.12	17.57	171190	175670
wire	non noble metal	copper	7440-50-8	0.037	0.09	0.09	930	930
encapsulation	organic material	carbon black	1333-86-4	0.038	0.10		950	
	plastics	epoxy resin	-	1.946	4.89		48935	
	inorganic material	silicondioxide	60676-86-0	16.909	42.53	47.52	425206	475091
leadfinish	non noble metal	tin	7440-31-5	0.387	0.97	0.97	9735	9735
plating	noble metal	silver	7440-22-4	0.963	2.42	2.42	24206	24206
solder	non noble metal	tin	7440-31-5	0.028	0.07		708	
	noble metal	silver	7440-22-4	0.035	0.09		886	
	non noble metal	lead	7439-92-1	1.345	3.38	3.54	33828	35422
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		108	
	non noble metal	iron	7439-89-6	0.086	0.22		2168	
	non noble metal	copper	7440-50-8	3.501	8.80	9.03	88042	90345
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002			47	
	non noble metal	zinc	7440-66-6	0.008	0.02		190	
	non noble metal	iron	7439-89-6	0.151	0.38		3795	
	non noble metal	copper	7440-50-8	6.127	15.41	15.81	154078	158110
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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